

BGA Pad = 0.2mm
BGA Pad soldermask = 0.3009mm
BGA Via = 0.3048 Pad
 0.1524 Drill
Blind Via = 0.3048 Pad
(TOP-SIGNAL1) 0.1524 Drill
BGA Tracks = 0.1016mm Width
 0.0889mm Spacing

NO OF LAYERS = 6

_____	TOP LAYER
_____	POWER LAYER
_____	SIGNAL1 LAYER
_____	SIGNAL2 LAYER
_____	GND LAYER
_____	BOTTOM LAYER

